

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CS22 Series Connector System	SPEC.NO.: SPCS011E
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1. SCOPE:

This specification contains the test requirement of subject PLCC chip carrier socket when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: CS22 Series

4. SHAPE,CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED : Eisley APPROVED : Sun VERIFIED : Karen .

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#### 7. ELECTRICAL PERFORMANCE:

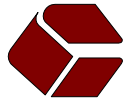
	ITEM	TEST CONDITION	
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 30 mΩ
7.3	Dielectric strength	When applied AC 600 V 1minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

#### 8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push pin from insulator base at speed 25±3 mm per minute	More than 400 gram
8.2	Durability	Connector shall be subject to 5 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

#### 9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10-55-10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.2	Solderability	Tin-Lead Process Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5°C Lead-Free Process Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area
9.3	Resistance to soldering heat	Refer Reflow temperature profile	No damage
9.4	Heat aging	105 ± 2°C, 96 hours	No damage



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	ITEM	TEST CONDITION	REQUIREMENT
9.5	Humidity	40 ± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.6	Temperature cycling	One cycle consists of : (1)-55 <sup>+0</sup> <sub>-3</sub> °C , 30 min. (2)Room temp. 10-15 min. (3) 85 <sup>+3</sup> <sub>-0</sub> °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.7	Salt spray	Temperature: 35±3°C Solution: 5±1% Spray time: 48±4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

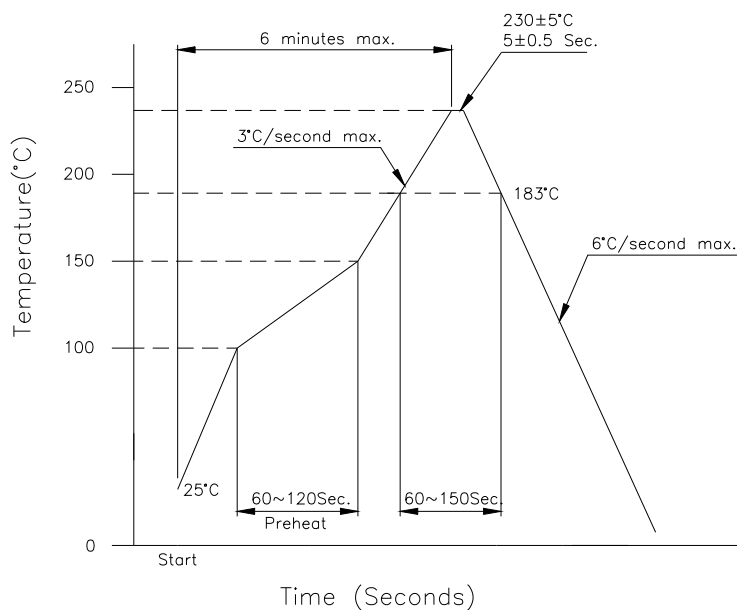
10. AMBIENT TEMPERATURE RANGE:

-40 to + 105°C ; +215°C intermittent (Vapor Phase Solder Reflow ) for SMT type

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## 11. Recommended IR Reflow Temperature Profile:

### 11.1 Using Typical Solder Paste



### 11.2 Using Lead-Free Solder Paste

